



## MEI Stack-up

### Texas Instruments

### TSW2200 Rev A

<u>Overall Thickness</u>		<b>.062</b>	<b>+/- 10%</b>	FR-4 170 Tg Er (Dielectric Constant) = 4.3	
		<u>Dielectric</u>		<u>Finished</u> <u>Copper</u>	
<b>Start with .38 oz cu</b>	1	-----	Signal	<b>1.5</b>	oz
		<b>.0082</b>			
	2	-----	Plane	<b>1</b>	oz
		<b>.039</b>			
	3	-----	Plane	<b>1</b>	oz
		<b>.0082</b>			
<b>Start with .38 oz cu</b>	4	-----	Signal	<b>1.5</b>	oz
		<b>.0624</b>	Final Thickness (After Plating)		

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- 1) Stack-up is for reference only.  
Please include approved stack-up in Final Data Package.
- 2) Some laminates require special order and additional lead time.  
Please confirm material availability with inside sales personnel.